

**ABSTRACT OF THE DISCLOSURE**

A semiconductor storage device enables various plural memories to be mounted on the same package, and even though size of respective chips and / or position of bonding pad are different, it is capable of providing a stack MCP in which the chips are superimposed. It causes wiring sheet to intervene between an upper chip and a lower chip. There are provided a bonding pad 12, a bonding pad 13, and a wiring pattern for connecting these bonding pads in the wiring sheet. A bonding pad 4 of the upper chip is connected to the bonding pad 12 by a first bonding wire, while the bonding pad 13 is connected to a bonding pad 5 of the package substrate by a second bonding wire. According to this constitution, the signal from the upper chip is transmitted to the package substrate while relaying by the wiring sheet.

5  
10